

PRELIMINARY SPEC

Part Number: KM-27SYCK-09

Super Bright Yellow

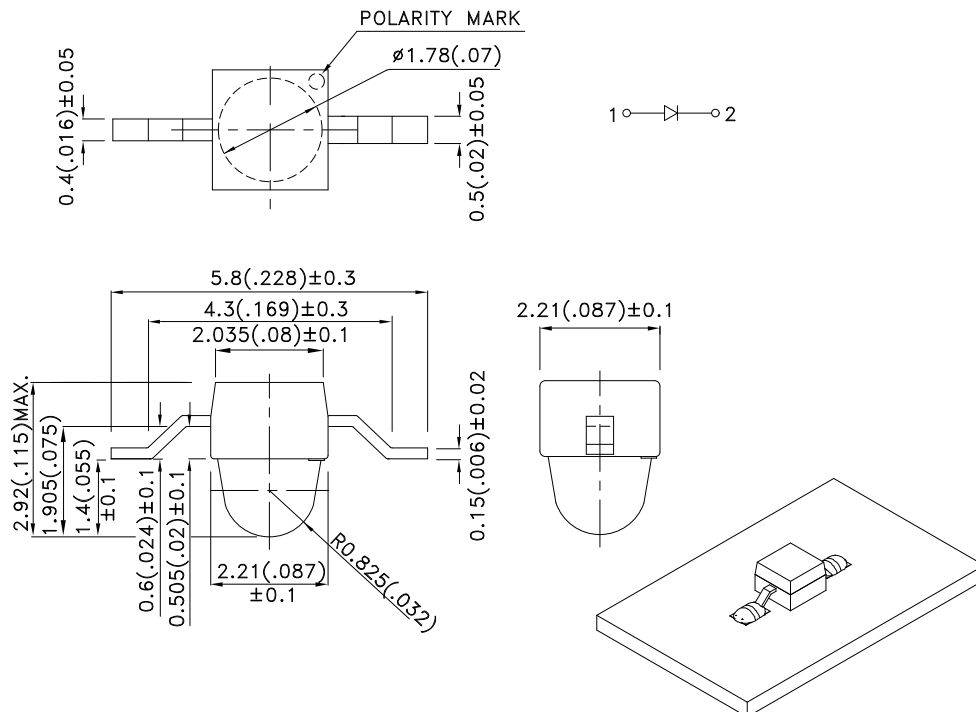
Features

- SUBMINIATURE PACKAGE.
- WIDE VIEWING ANGLE.
- Z-BEND LEAD.
- LONG LIFE - SOLID STATE RELIABILITY.
- LOW PACKAGE PROFILE.
- PACKAGE :1000PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 3.
- RoHS COMPLIANT.

Description

The Super Bright Yellow device is made with InGaAlP (on GaAs substrate) light emitting diode chip.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ " unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. Specifications are subject to change without notice.
5. The device has a single mounting surface. The device must be mounted according to the specifications.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
KM-27SYCK-09	Super Bright Yellow (InGaAlP)	WATER CLEAR	650	1300	20°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ _{peak}	Peak Wavelength	Super Bright Yellow	590		nm	I _F =20mA
λ _D [1]	Dominant Wavelength	Super Bright Yellow	590		nm	I _F =20mA
Δλ _{1/2}	Spectral Line Half-width	Super Bright Yellow	20		nm	I _F =20mA
C	Capacitance	Super Bright Yellow	20		pF	V _F =0V;f=1MHz
V _F [2]	Forward Voltage	Super Bright Yellow	2	2.5	V	I _F =20mA
I _R	Reverse Current	Super Bright Yellow		10	uA	V _R =5V

Notes:

1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

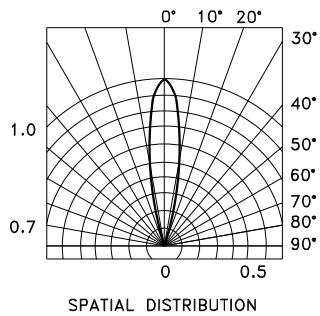
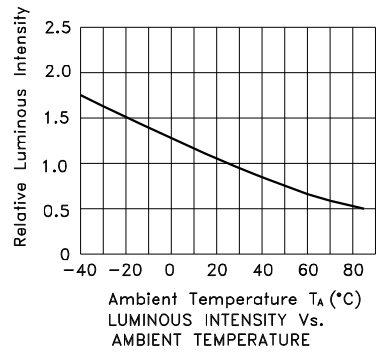
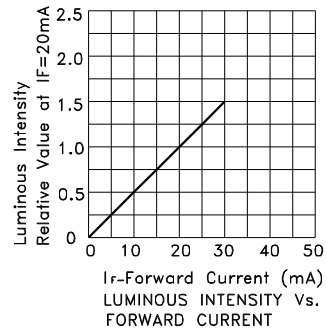
Parameter	Super Bright Yellow	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	175	mA
Reverse Voltage	5	V
Operating Temperature	-40°C To +85°C	
Storage Temperature	-40°C To +85°C	

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



Super Bright Yellow KM-27SYCK-09



KM-27SYCK-09

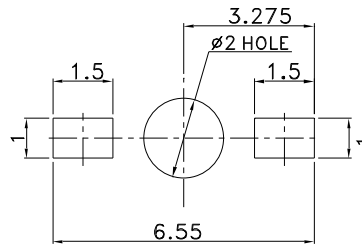
Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Tape Specifications (Units : mm)

